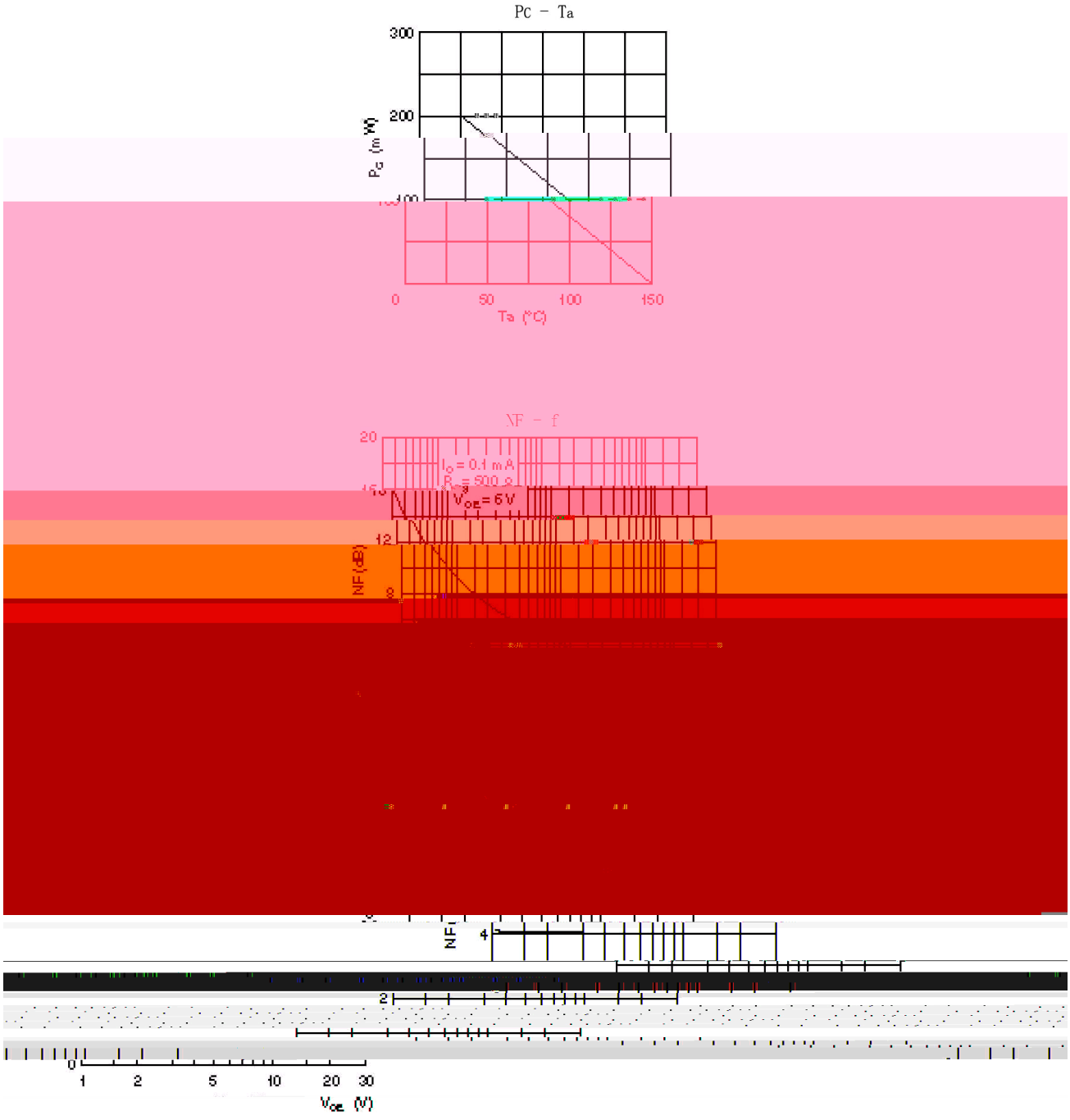
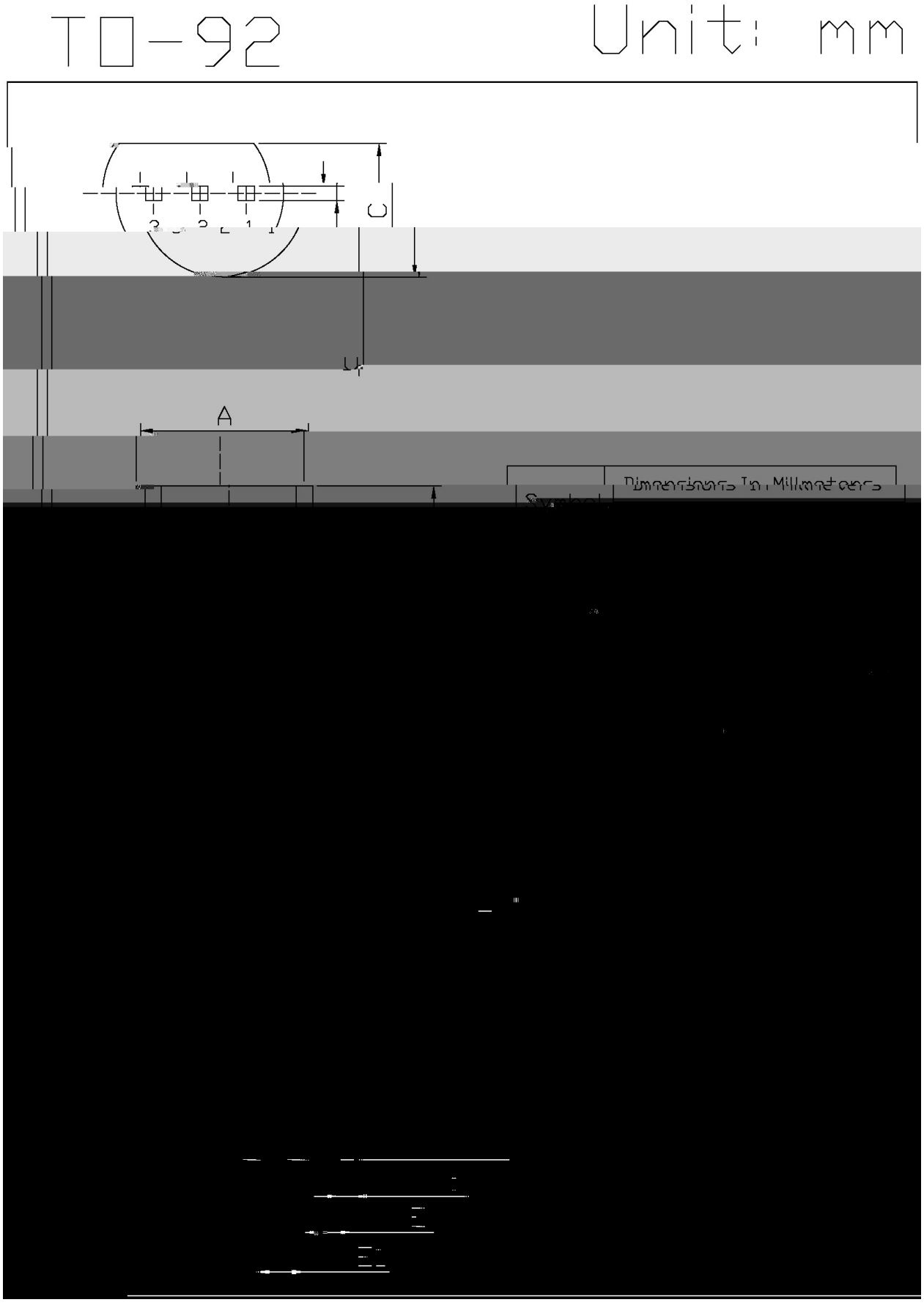
WR0<5 ṂṂ Ƚ QSQ ÆṀ ɥ s ǁ ˥ Silicon NPN transistor in

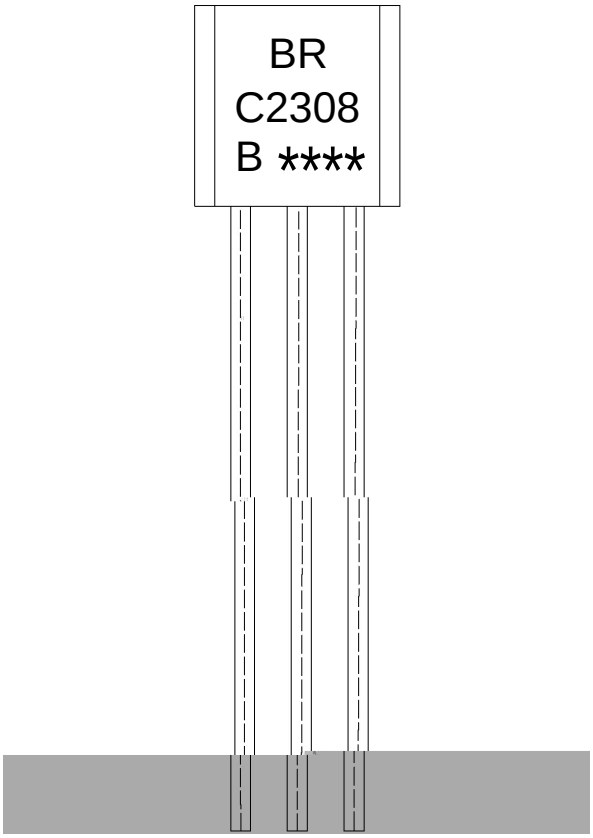
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



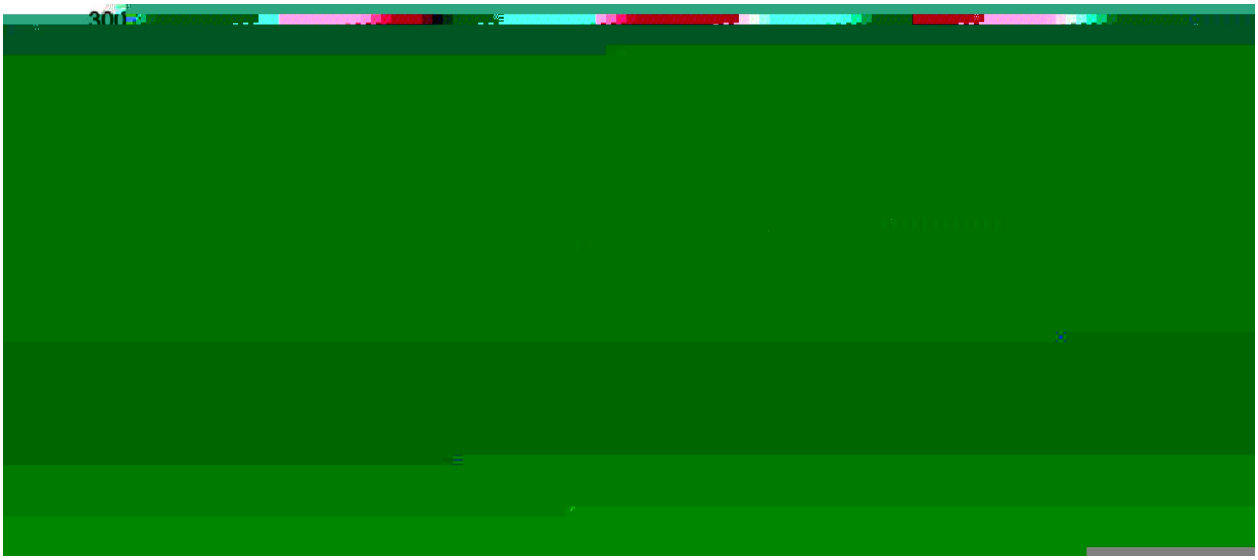
ب ˝ χ

EU=	ѭ ʒ ᴵᴵ Ɱ
F563 ; χ	ѭ ʒ ᴺ Ɱ
E=	ѭ kᴵᴴ ʻ ᶠ Ɱ
---- χ	ѭ ɨ ɾ ŋ̈ ᴺ Ɱ ɪ ɐ ɨ ɾ ŋ̈ ᴺ ψ ק

Note:

BR:	Company Code.
C2308:	Product Type.
B:	h_{FE} Classifications Symbol
****:	Lot No. Code,code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 ƚ ♬ □ ỷ 25 Ḱ 150 ɬ ı ̀H ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 255 ° 5 ɬ ı ̀H ڑ ̀Y ⺈ ⺮ 5 ° 0.5sec;

3 ì ̇ ⺈ ̨ ɔ ھ ỷ ⺮ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:25~150 ɬ , Time:60~90sec.

2.Peak Temp.:255 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ɬ ̀H ڑ χ 10 ° 1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

̈Ω̣ ţ ɣ ŁŁ / BULK

Package Type	Units	Dimension	(unit mm3)